



Material declaration form

General Information			
IPC	1752	Version	2
Form type*	Distribute		
Sectionals*	Material information	Subsectionals*	A-D
	Manufacturing information		

Supplier Information			
Company name*	STMicroelectronics	Response Date*	2023-10-17
Contact name*	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact phone*	Refer to Supplier Comment section	Contact email*	Refer to Supplier Comment section
Authorized representative*	giovanni giacopello	Representative title	ADGMaterial Declaration champion
Representative phone*	Refer to Supplier Comment section	Representative email*	Refer to Supplier Comment section
Supplier comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty statement

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Legal statement

Supplier acceptance*	true	Legal declaration*	Standard
Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.			



Product				
Mfr item number	Mfr item name	Version	Manufacturing site	date
L9969U-TR	STEH*UR6SCBQ	A	959	2023-10-17
	Amount	Unit of measure	Unit type	ST ECOPACK grade
	484.00	mg	Each	ECOPACK® 2
Identity	Authority			
Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)			

Manufacturing information				
J-STD-020 MSL rating	Classification temperature	Number of reflow cycles		
3	260	3		
Bulk solder termination	Terminal plating	Terminal base alloy	Comment	
Not Applicable	Tin (Sn), matte, annealed	Copper Alloy	DM00838839	
Package designator	Package size	Number of instances	Shape	
QFP	10.30x7.50x2.28	36	Gull wing	
Comment	PowerSSO36			



QueryList : RoHS Directive 2011/65/EU- 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015		Response
1 - Product(s) meets EU RoHS requirement without any exemptions		false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)		false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)		true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions		false
Exemption Id.	Description	
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)	

QueryList : ELV directive : 2000/53/EC amended 2020/363_March 2020		Response
1 - Product(s) meets EU ELV requirements without any exemptions		false
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)		true
Exemption Id.	Description	
8(e)	8(e) - Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead)	

QueryList : California Prop65 list, dated 25th Feb 2022			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			false
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			true
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.015	die	31
Lead	2.319	soft solder	4791

QueryList : REACH-14th June 2023				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				false
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
Lead	1000 ppm	2.32	Soft solder	4791
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				false
CategoryLevel_Name	CategoryLevel_Threshold	Amount in embedded article / Homogeneous material (mg)	Application - article / Homogeneous material	ppm in article /Homogeneous material
Lead	1000 ppm	2.32	Soft solder	974779

QueryList : Responsible metals sourcing	Response
The component is containing at least one of the following metals : Cobalt , Gold , Tantalum , Tin , Tungsten.	true
The following metals are present is the component :	Cobalt, Gold, Tin, Tungsten,

QueryList : Korea Chemical Control Act_ 27 Dec 2017 update	Response
The Product does contain at least one of the substances listed in Chemical Control Act	false

QueryList : China GB 33372-2020 Limit standard for volatile organic compounds content in adhesives - 4 March 2020 application date 1st December 2020	Response
The product contains adhesives identified under GB 33372	false

Stockholm Convention Persistent Organic Pollutants	Response
Product is compliant with Stockholm Convention Persistent Organic Pollutants Annex I	true

QueryList : EUSRR Directive	Response
Product contains hazardous materials listed in EUSRR Annex II	True
	Lead

PFAS/PTFE Restriction	Response
Product contains Per- and Polyfluorinated Substance	False

BPA Restriction	Response
Product contains Bisphenol A (Isopropylidenediphenol)	False



Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	STEH*UR6SCBQ									
Homogeneous material	Material group	Mass	Unit of measure	Level	Substance category	Substance	CAS	Exempt	Mass	Unit of measure	Concentration in homogeneous material (ppm)	Concentration in product (ppm)				
Die	M-011 Other inorganic materials	5.725	mg	supplier	die	Silicon(Si)	7440-21-3		5.197	mg	907773	10736				
				supplier	metallisation	Chromium(Cr)	7440-47-3		0.003	mg	524	6				
				supplier	metallisation	Copper(Cu)	7440-50-8		0.354	mg	61834	731				
				supplier	metallisation	Cobalt(Co)	7440-48-4		0.001	mg	175	2				
				supplier	metallisation	Gold(Au)	7440-57-5		0.008	mg	1397	17				
				supplier	metallisation	Nickel(Ni)	7440-02-0		0.015	mg	2620	31				
				supplier	metallisation	Palladium(Pd)	7440-05-3		0.013	mg	2271	27				
				supplier	metallisation	Tungsten(W)	7440-33-7		0.016	mg	2795	33				
				supplier	metallisation	Vanadium(V)	7440-62-2		0.001	mg	175	2				
				supplier	passivation	Silicon oxide	7631-86-9		0.057	mg	9956	118				
				supplier	polymer coating	polyimide	proprietary		0.060	mg	10480	124				
				Leadframe	M-004 Copper and its alloys	161.646	mg	supplier	alloy	Copper(Cu)	7440-50-8		155.390	mg	961298	321054
								supplier	alloy	Iron(Fe)	7439-89-6		3.655	mg	22611	7552
supplier	alloy	Iron phosphide	1310-43-6						0.220	mg	1361	455				
supplier	alloy	Zinc(Zn)	7440-66-6						0.191	mg	1182	395				
supplier	metallization	Silver (Ag)	7440-22-4						2.190	mg	13548	4525				
supplier	alloy	Lead(Pb)	7439-92-1					7a-Lead in high melting temperat	2.319	mg	974780	4791				
Soft solder	Solder	2.379	mg	SVHC	solder	Lead(Pb)	7439-92-1	7a-Lead in high melting temperat	2.319	mg	974780	4791				
				supplier	solder	Silver(Ag)	7440-22-4		0.036	mg	15132	74				
				supplier	solder	Tin(Sn)	7440-31-5		0.024	mg	10088	50				
Bonding wires	M-004 Copper and its alloys	1.512	mg	supplier	wire	Copper(Cu)	7440-50-8		1.512	mg	1000000	3124				
Encapsulation	M-011 Other inorganic materials	308.486	mg	supplier	mold compound	Silica vitreous	60676-86-0		273.010	mg	884999	564070				
				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		16.350	mg	53001	33781				
				supplier	mold compound	Phenol resin	205830-20-2		12.339	mg	39999	25494				
				supplier	mold compound	Epoxy type resin	25068-38-6		6.170	mg	20001	12748				
				supplier	mold compound	Carbon black	1333-86-4		0.617	mg	2000	1275				
Connections coating	Solder	4.252	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		4.252	mg	1000000	8785				